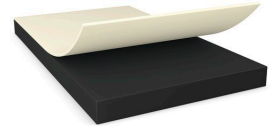




58702

제품 정보



50µ x-linkable polyurethane black HAF mounting

제품 설명

tesa® XPU 58702 is a reactive mounting tape offering high bonding strength and elasticity after curing. This black double-sided tape has no backing. It is protected by a PE-coated paper liner.

Black design

특성

- Extremely high bonding performance and reliability, even on thin design gaps
- Extremely low oozing ratio
- Excellent shock resistance
- It is activated by heat and pressure applied during the assembly process.
- At room temperature tesa® XPU 58702 is not tacky.
- tesa® XPU 58702 is free of halogen according to IEC 61249-2-21 and compliant with current RoHS directive.

Applications

tesa® XPU 58702 is especially recommended for structural bonding of various substrates inside electronic devices:

- Bonding of plastics
- Bonding of metals
- Bonding of electronic components

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

제품 구조

- | | | | |
|----------|----------------------------|-------|-------|
| • 기재 소재 | 없음 | • 총두께 | 50 µm |
| • 점착제 종류 | crosslinkable polyurethane | • 컬러 | 검정 |
| • 이형지 종류 | PE 코팅된 직물 | | |

속성 / 성능 값

- 점착력 (푸쉬 아웃) 2.5 N/mm²

관련제품 최신자료는 다음의 경로를 클릭하세요 <http://l.tesa.com/?ip=58702>



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제품 정보

추가정보

Technical recommendations:

tesa® XPU 58702 is not self-adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

- Pre-lamination

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

Temperature¹ 55-65 °C

Pressure² 3 bar

Time 5 – 20 s

Short-time exposure to 65 °C bond line temperature during pre-lamination does not affect the final bonding potential.

2. Bonding

Remove the liner from tape after the pre-lamination step. Position the second component.

Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

2.1. PC/PC: Setting:

- Temperature¹ 80 – 140 °C

- Pressure² 5 bar

- Time 10 – 120 s

2.2. AL/PC: Setting:

- Temperature¹ 110 – 190 °C

- Pressure² 5 bar

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제품 정보

추가정보

- Time 20 – 120 s

Short cycle times can be achieved at high bond line temperatures. For activation at low temperatures, increase the heat-press time. To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours. Bonding strength values were obtained under standard laboratory conditions. PC/PC: bonding conditions: temperature = 110 °C (120 °C jig); pressure = 5 bar; time = 60 sec Storage: tesa® recommends storage in original packaging in cool and dry conditions.

- 'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

공지사항

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